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(54) Title: COMPOSITION COMPRISING STYRENE ISOBUTYLENE BLOCK COPOLYMER AND ETHYLENICALLY UNSATURATED MONOMER

(57) Abstract: A composition is described comprising a styrene-isobutylene block copolymer; and at least one ethylenically unsaturated monomer. After curing the composition comprises polymerized units of the ethylenically unsaturated monomer. In some embodiments the ethylenically unsaturated groups are selected from (meth)acryl or vinyl ether. The composition is suitable for use as a (e.g. pressure sensitive) adhesive. Articles, methods of making an article, and methods of bonding are also described.



5 **COMPOSITION COMPRISING STYRENE ISOBUTYLENE BLOCK COPOLYMER
AND ETHYLENICALLY UNSATURATED MONOMER**

Summary

10 In one embodiment, a composition is described comprising a styrene-isobutylene block copolymer; and at least one ethylenically unsaturated monomer.

 In another embodiment, a composition is described comprising a styrene-isobutylene block copolymer; and polymerized units of at least one ethylenically unsaturated monomer comprising one or more groups selected from (meth)acryl or vinyl ether.

15 In another embodiment, a method of making an article is described comprising providing the composition described herein; applying the composition to a substrate; and optionally curing the at least one ethylenically unsaturated monomer. In one embodiment, the composition further comprises a free-radical initiator and the method comprises curing the ethylenically unsaturated monomer by exposing the composition to actinic radiation, such as ultraviolet (UV) or visible light.

20 In another embodiment, an article is described comprising a substrate; the composition described herein disposed on the substrate. In some embodiments, the substrate is a release liner, a film, or an electronic component.

 In another embodiment, a method of bonding is described comprising providing the composition described herein; and bonding a substrate to a second substrate or surface with the
25 composition.

 In each of these embodiments, the ethylenically unsaturated monomer may be a monofunctional or multifunctional ethylenically unsaturated monomer. In some embodiments, the ethylenically unsaturated monomer is aliphatic and in some embodiments preferably aromatic, having a refractive index of at least 1.50, 1.55, or 1.60.

30 In some embodiments, the ethylenically unsaturated monomer has a hydrophilic-lipophilic balance (HLB) ranging from 3.7 to 7.3 and/or a Moriguchi Log P ranging from 1.8 to 6.

 In some embodiments, the composition further comprises an additive, such as a tackifier.

 The composition is suitable for use as a coating, encapsulant, or adhesive, especially a pressure sensitive adhesive.

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Detailed Description

 Presently described is a composition comprising a styrene-isobutylene block copolymer. The block copolymer comprises styrene end blocks and a saturated butylene, in particular isobutylene-containing midblock. The block copolymer typically comprises a styrene-isobutylene-

5 styrene triblock copolymer (SIBS). The block copolymer may further comprise styrene-isobutylene diblock copolymer (SIB).

The weight average molecular weight (Mw) of the styrene-isobutylene block copolymer is typically at least 10,000; 15,000; 20,000; 25,000; or 30,000 g/mole. The weight average molecular weight (Mw) of the styrene-isobutylene block copolymer is typically no greater than 200,000
10 g/mole. In some embodiments, the weight average molecular weight (Mw) is no greater than 175,000; 150,000; 125,000; or 100,000 g/mole.

The styrene content of the styrene-isobutylene block copolymer is preferably at least 10 or 15 wt.-% styrene ranging up to 30, 35, 40, 45 or 50 wt.-% styrene, based on the total weight of the styrene-isobutylene block copolymer.

15 In some embodiments, the composition comprises at least 5, 10, 15, 20, 25, 30, 35, 40, 45, or 50 wt.-% of styrene-isobutylene block copolymer. In some embodiments, the composition comprises no greater than 99, 98, 97, 96, or 95 wt.-% of styrene-isobutylene block copolymer. In some embodiments, the composition comprises no greater than 90, 85, 80, 75, 70, 65, or 60 wt.-% of styrene-isobutylene block copolymer. The styrene-isobutylene block copolymer may be a
20 single polymer or a combination of two or more styrene-isobutylene block copolymers.

In some embodiments, the composition comprises styrene-isobutylene block copolymer with little or no polyisobutylene polymer. In other embodiments, the composition comprises styrene-isobutylene block copolymer component (SIBS) block copolymer in combination with (e.g. at least about 4 or 5 wt.-%) of polyisobutylene polymer, as will subsequently be described.

25 The composition can contain various ethylenically unsaturated (e.g. free-radically polymerizable) monomers that can provide various technical benefits. The ethylenically unsaturated monomer is a different monomer than use in the preparation of the SIBS block copolymer. Thus, the ethylenically unsaturated monomer is not styrene, isobutylene or other alkene comonomers (e.g. butene) that are typically present in the SIBS block copolymer. The
30 ethylenically unsaturated monomer typically comprises (meth)acryl or vinyl ether groups. The term “meth(acryl)” includes (meth)acrylate and (meth)acrylamide.

In some embodiments, the ethylenically unsaturated (e.g. free-radically polymerizable) monomer is monofunctional, comprising a single ethylenically unsaturated (e.g. free-radically polymerizable) group. In other embodiments, the monomer is multifunctional, comprising at least
35 2, 3, 4, 5, or 6 ethylenically unsaturated (e.g. free-radically polymerizable) groups. Suitable ethylenically unsaturated (e.g. free-radically polymerizable) groups include for example (meth)acrylate, (meth)acrylamide, vinyl ether groups, and alkenyl. The multifunctional monomers can comprise different ethylenically unsaturated (e.g. free-radically polymerizable) groups on the same monomer.

5 In typical embodiments, the molecular weight of the ethylenically unsaturated monomer is at least 200 g/mole, 250 g/mole, 300 g/mole, 350 g/mole, 400 g/mole, or 450 g/mole. In typical embodiments, the molecular weight is less than 2500, 2000, or 1500 g/mole.

The composition can contain a single monofunctional monomer, a single multifunctional monomer, or various combinations thereof. The combinations can include at least two
10 monofunctional monomers, at least two multifunctional monomers, as well as at least one monofunctional monomer(s) in combination with at least one multifunctional monomer(s).

The composition can contain a single aliphatic monomer, a single aromatic monomer, or various combinations thereof. The combinations can include at least two aliphatic monomers, at least two aromatic monomers, as well as at least one aliphatic monomer(s) in combination with at
15 least one aromatic monomer(s).

The total amount of ethylenically unsaturated monomer can vary. For example, the composition may contain only a small amount of ethylenically unsaturated monomer for the purpose of adjusting the adhesion or cohesive strength of the composition. Higher concentrations may be used for the purpose of raising the refractive index. Thus, in some embodiments, the
20 composition comprises at least 1, 2, 3, 4, or 5 wt.-% of ethylenically unsaturated monomer(s). In some embodiments, the composition comprises 6, 7, 8, 9, 10, 11, 12, 13, 14 or 15 wt.-% of ethylenically unsaturated monomer(s). The amount of ethylenically unsaturated monomer(s) is typically no greater than 50, 45, 40, 35, 30, 25, or 20 wt.-% of the composition.

In some embodiments, the ethylenically unsaturated (e.g. free-radically polymerizable)
25 monomer is aliphatic. Aliphatic ethylenically unsaturated monomer have a lower refractive index than aromatic ethylenically unsaturated monomer. Aliphatic ethylenically unsaturated monomers, can usefully be employed to adjust the properties of the composition. For example, monomers such as octyl acrylate or 2-ethylhexyl acrylate can be used to increase adhesion. Alternatively, or in combination thereof, multifunctional monomers, such as hexane diol di(meth)acrylate or
30 trimethylolpropane tri(meth)acrylate, can be used to increase the cohesive strength.

Examples of aliphatic monofunctional ethylenically unsaturated monomers include acrylic acid, methacrylic acid, and crotonic acid; (meth)acrylic acid alkyl esters such as lauryl acrylate; hydroxyl group-containing (meth)acrylic acid esters such as 2-hydroxyethyl acrylate, 2-hydroxypropyl acrylate, 4-hydroxybutyl acrylate, tetrahydrofurfuryl acrylate, and the like.

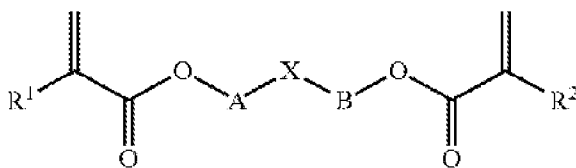
35 Other examples of aliphatic multifunctional ethylenically unsaturated (e.g. free-radically polymerizable) monomers include 1,4-butanediol di(meth)acrylate, 1,6-hexanediol di(meth)acrylate, neopentyl glycol di(meth)acrylate, polyethylene glycol di(meth)acrylate, neopentyl glycol adipate di(meth)acrylate, hydroxyphenyl glycol di(meth)acrylate, dicyclopentenyl di(meth)acrylate, caprolactone-modified dicyclopentenyl di(meth)acrylate,

ethylene oxide-modified phosphoric acid di(meth)acrylate, allylated cyclohexyl di(meth)acrylate, isocyanurate di(meth)acrylate, trimethylolpropane tri(meth)acrylate, dipentaerythritol tri(meth)acrylate, propionic acid-modified dipentaerythritol tri(meth)acrylate, pentaerythritol tri(meth)acrylate, propylene oxide-modified trimethylolpropane tri(meth)acrylate, tris(acryloyloxyethyl) isocyanurate, propionic acid-modified dipentaerythritol penta(meth)acrylate, dipentaerythritol hexa(meth)acrylate, and caprolactone-modified dipentaerythritol hexa(meth)acrylate.

In some embodiments, the aliphatic multifunctional ethylenically unsaturated (e.g. free-radically polymerizable) monomer is a urethane (meth)acrylate oligomer, a polyester (meth)acrylate oligomer, or an epoxy (meth)acrylate oligomer.

In some embodiments, the aliphatic ethylenically unsaturated (e.g. free-radically polymerizable) monomers comprise a cyclic group. The number of carbon atoms of the aliphatic cyclic group is typically at least 3, 4, 5, or 6 ranging up to 20 or 30. Specific examples cycloalkanes such as cyclopropane, cyclobutane, cyclopentane, and cyclohexane, a polycyclic cycloalkane such as norbornane, adamantane, tricyclodecane, and tetracyclododecane, a monocyclic cycloalkene such as cyclopropene, cyclobutene, cyclopentene, and cyclohexene, a polycyclic cycloalkene such as norbornene, tricyclodecene, and tetracyclododecene, and the like.

Specific examples of difunctional cycloaliphatic compounds can be represented by the following formula (I).



wherein X is a divalent cyclic hydrocarbon group, as just described;

R¹ and R² are independently hydrogen or methyl; and

A and B are independently a covalent bond or an alkylene groups having at 1 to 10 carbon atoms and in some embodiments no greater 6, 5, 4, or 3 carbon atoms.

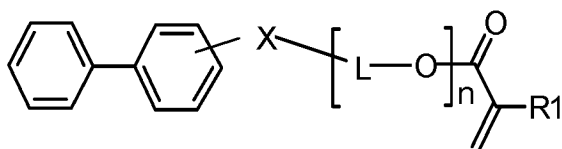
In favored embodiments, the ethylenically unsaturated (e.g. free-radically polymerizable) monomer is aromatic. Aromatic monomers can be used to raise the refractive index of the (e.g. adhesive) composition. This can be beneficial to index-match the composition to a transparent substrate to which the composition is applied. Higher refractive index compositions can also be used to cover conductive traces, such as indium-tin-oxide or metal (e.g. silver) nanowires.

In some embodiments, the refractive index of the ethylenically unsaturated (e.g. free-radically polymerizable) monomer is at least 1.50, 1.51, 1.52, 1.53, 1.54, 1.55, 1.56, 1.57, 1.58, 1.59, 1.60, 1.61, 1.62, or 1.63. The refractive index of the ethylenically unsaturated monomer is typically no greater than 1.77, 1.76, 1.75, 1.74, 1.73, 1.72, 1.71 or 1.70. Aromatic ethylenically unsaturated monomers typically comprise aromatic groups such as phenyl (e.g. biphenyl, triphenyl, etc.), naphthyl, fluorene, etc. The ethylenically unsaturated monomer may be halogenated or non-halogenated.

Inclusion of a high refractive index ethylenically unsaturated (e.g. free-radically polymerizable) monomer can raise the refractive index of the (e.g. adhesive) composition by at least 0.01, 0.02, 0.03, 0.04, 0.05 or greater.

Suitable monofunctional aromatic monomers include for example phenoxy ethyl (meth)acrylate; phenoxy-2-methylethyl (meth)acrylate; phenoxyethoxyethyl (meth)acrylate; phenylthiol ethyl (meth)acrylate; 3-hydroxy-2-hydroxypropyl (meth)acrylate; benzyl (meth)acrylate; phenylthio ethyl acrylate; 2-naphthylthio ethyl acrylate; 1-naphthylthio ethyl acrylate; 2,4,6-tribromophenoxy ethyl acrylate; 2,4-dibromophenoxy ethyl acrylate; 2-bromophenoxy ethyl acrylate; 1-naphthyloxy ethyl acrylate; 2-naphthyloxy ethyl acrylate; phenoxy 2-methylethyl acrylate; phenoxyethoxyethyl acrylate; 3-phenoxy-2-hydroxy propyl acrylate; 2,4-dibromo-6-sec-butylphenyl acrylate; 2,4-dibromo-6-isopropylphenyl acrylate; and 2,4,6-tribromophenyl acrylate.

In one embodiment, the composition comprises a biphenyl ethylenically unsaturated monomer having the general formula:



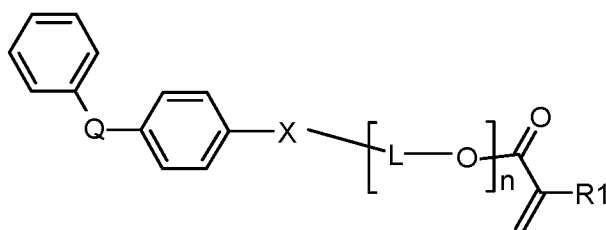
wherein R1 is H or CH₃;

X is O or S;

n ranges from 0 to 10 (e.g. n is 1, 2, 3, 4, 5, 6, 7, 8, 9, or 10); and

L is an alkylene group having 1 to 5 carbon atoms (i.e. methylene, ethylene, propylene, butylene, or pentylene), optionally substituted with hydroxy.

In another embodiment, the composition comprises an aromatic ethylenically unsaturated monomer having the general formula:



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wherein R1 is H or CH₃;

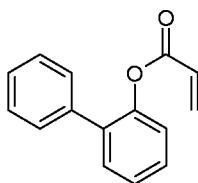
X is O or S;

Q is selected from C(CH₃)₂, CH₂, C(O), S(O), S, and S(O)₂;

n ranges from 0 to 10 (e.g. n is 1, 2, 3, 4, 5, 6, 7, 8, 9, or 10); and

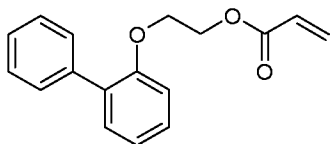
10 L is an alkylene group having 1 to 5 carbon atoms, optionally substituted with hydroxy.

One representative monomer, 2-phenyl-phenyl acrylate, is commercially available from Toagosei Co. Ltd. of Japan under the trade designation "TO-2344" is depicted as follows:



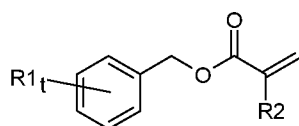
15 Another biphenyl (meth)acrylate monomer is 4-(-2-phenyl-2-propyl)phenyl acrylate, available from Toagosei Co. Ltd. under the trade designation "TO-2345". Yet another biphenyl (meth)acrylate monomer, 2-phenyl-2-phenoxyethyl acrylate, available from Toagosei Co. Ltd. under the trade designation "TO-1463" and under the trade designation "M1142" from Miwon Specialty Chemical Co. Ltd., Korea, is depicted as follows:

20



In another embodiment, the composition comprises a benzyl ethylenically unsaturated monomer. Suitable benzyl (meth)acrylate monomers are described in PCT Publication No.

25 WO2012/158317; incorporated herein by reference. The benzyl (meth)acrylate monomer typically has the general formula:



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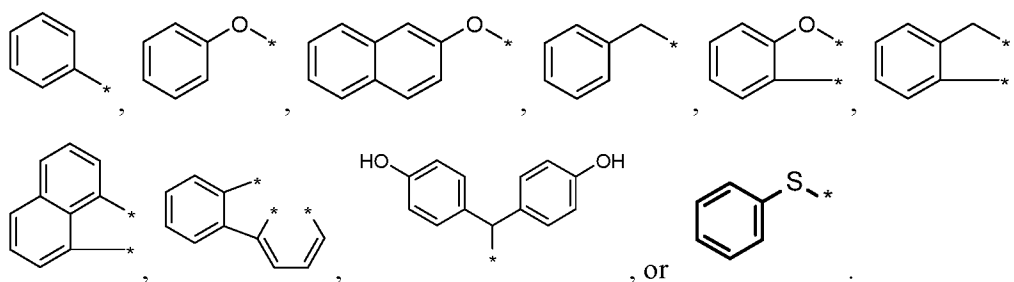
wherein at least one R1 comprises an aromatic substituent,

t is an integer from 1 to 4; and

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R2 is hydrogen or methyl.

R1 may comprise various aromatic substituents such as



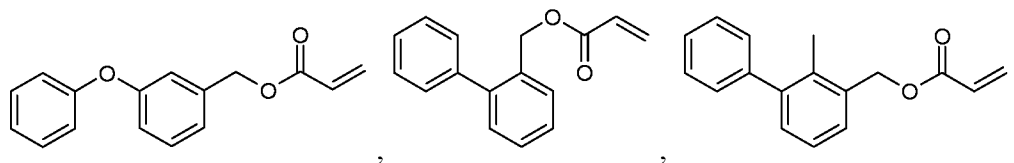
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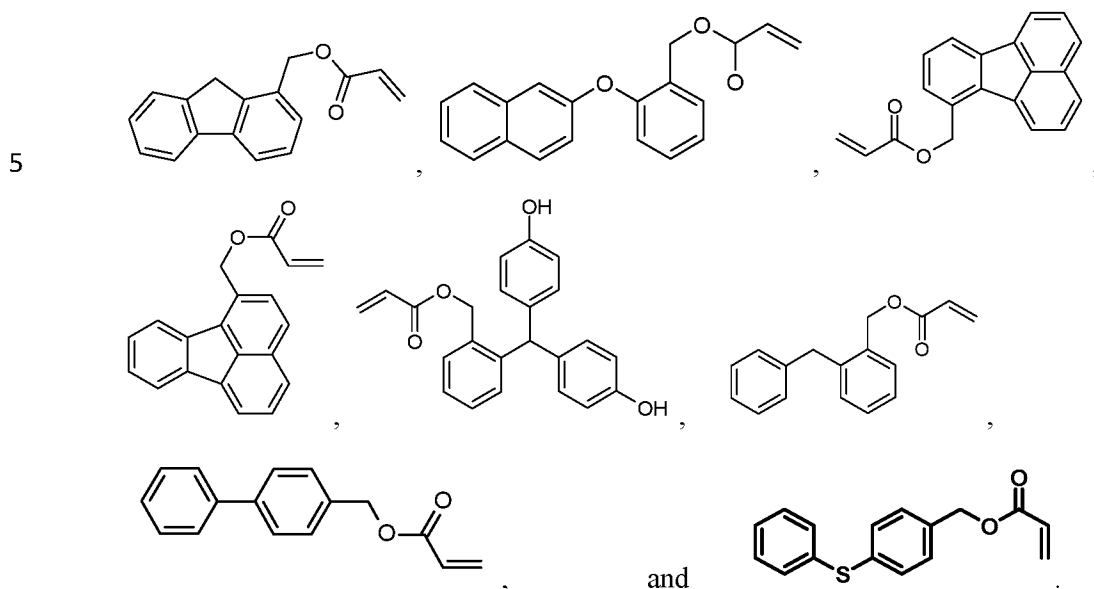
The aromatic substituent R1 is generally bonded to the aromatic ring of the benzyl group by at least one divalent (e.g. alkylene or ether) linking group. Hence, the aromatic ring of R1 is typically not fused to the aromatic benzyl ring, as in the case of naphthyl. In some embodiments, the aromatic substituent R1 is bonded to the aromatic benzyl ring by two or more divalent (e.g.

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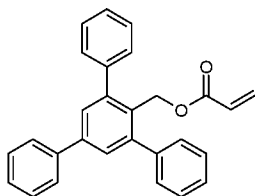
alkylene or ether) linking groups.

In some favored embodiments, t is 1. Representative structures include



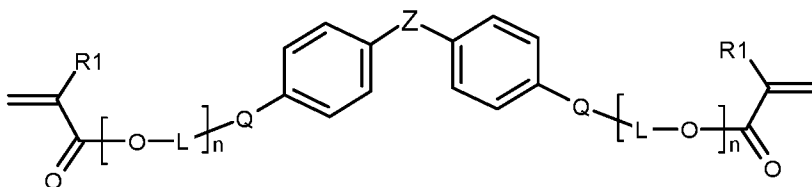


In other embodiments, t is greater than 1. For example, in one embodiment, t is 3. One representative structure is



The aromatic multifunctional ethylenically unsaturated monomer may be synthesized or purchased. The aromatic multifunctional ethylenically unsaturated monomer typically contains a major portion, i.e. at least 60-70 wt-%, of a specific structure. It is commonly appreciated that other reaction products are also typically present as a byproduct of the synthesis of such monomers.

In some embodiments, the aromatic multifunctional ethylenically unsaturated monomer comprises a major portion having the following general structure:



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wherein Z is independently $-\text{C}(\text{CH}_3)_2-$, $-\text{CH}_2-$, $-\text{C}(\text{O})-$, $-\text{S}-$, $-\text{S}(\text{O})-$, or $-\text{S}(\text{O})_2-$, each Q is independently O or S. L is a linking group. L may independently comprise a branched or linear C_2 - C_6 alkyl group and n ranges from 0 to 10. More preferably L is C_2 or C_3 and n is 0, 1, 2 or 3.

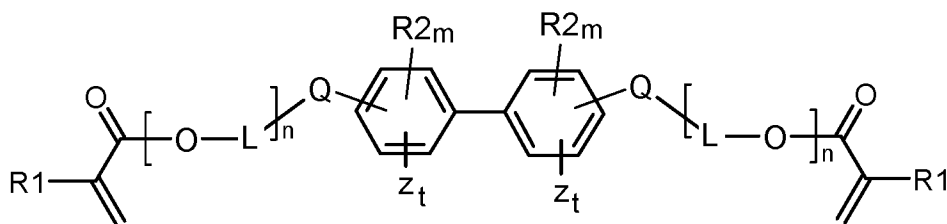
10 The carbon chain of the alkyl linking group may optionally be substituted with one or more hydroxy groups. For example L may be $-\text{CH}_2\text{CH}(\text{OH})\text{CH}_2-$. Typically, the linking groups are the same. R1 is independently hydrogen or methyl.

One bisphenol-A ethoxylated diacrylate monomer is commercially available from Sartomer under the trade designations "SR602" (reported to have a viscosity of 610 cps at 20°C and a Tg of 2°C). Another bisphenol-A ethoxylated diacrylate monomer is as commercially
15 available from Sartomer under the trade designation "SR601" (reported to have a viscosity of 1080 cps at 20°C and a Tg of 60°C).

Various (meth)acrylated aromatic epoxy oligomers are commercially available. For example, (meth)acrylated aromatic epoxy, (described as a modified epoxy acrylates), are available
20 from Sartomer, Exton, PA under the trade designation "CN118", and "CN115". (Meth)acrylated aromatic epoxy oligomer, (described as an epoxy acrylate oligomer), is available from Sartomer under the trade designation "CN2204". Further, a (meth)acrylated aromatic epoxy oligomer, (described as an epoxy novolak acrylate blended with 40% trimethylolpropane triacrylate), is available from Sartomer under the trade designation "CN112C60". One aromatic epoxy acrylate is
25 commercially available from Sartomer under the trade designation "CN 120" (reported by the supplier to have a refractive index of 1.5556, a viscosity of 2150 at 65°C , and a Tg of 60°C).

In some embodiments, the aromatic multifunctional ethylenically unsaturated monomer is a biphenyl multifunctional ethylenically unsaturated monomer. Such monomer may comprise a major portion having the following general structure:

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wherein each R1 is independently H or methyl;

35 each R2 is independently H or Br;

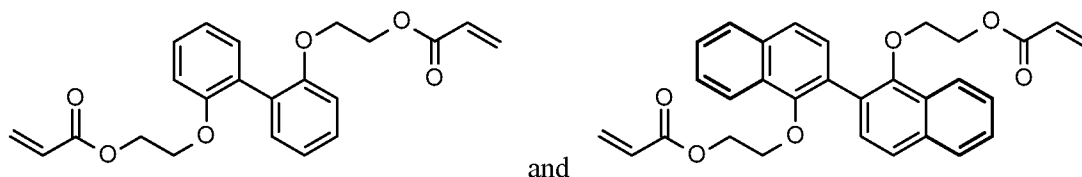
- 5 m ranges from 0 to 4;
 each Q is independently O or S;
 n ranges from 0 to 10;
 L is a C₂ to C₁₂ alkylene group optionally substituted with one or more hydroxyl groups;
 z is a (e.g. fused) aromatic ring; and
 10 t is independently 0 or 1.

In some embodiments, Q is preferably O. Further, n is typically 0, 1 or 2. L is typically C₂ or C₃. Alternatively, L is typically a hydroxyl substituted C₂ or C₃.

- Preferably, at least one of the $-Q[L-O]_n C(O)C(R_1)=CH_2$ groups is substituted at the ortho or meta position. More preferably, the biphenyl di(meth)acrylate monomer comprises a sufficient
 15 amount of ortho and/or meta (meth)acrylate substituents such that the monomer is a liquid at 25°C.

Such biphenyl monomers are described in further detail in U.S. Publication No. US2008/0221291. Other biphenyl di(meth)acrylate monomer are described in the literature.

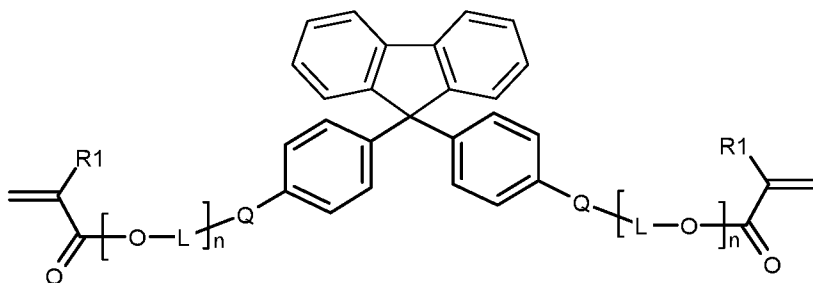
Representative structures wherein t is 0 or 1 include:



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In some embodiments, the aromatic monofunctional or multifunctional ethylenically monomer is a triphenyl monomer such as described in WO2008/112452; incorporated herein by reference.

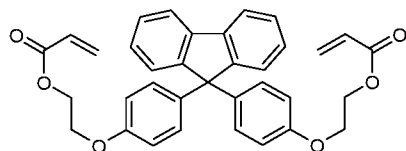
- In some embodiments, the aromatic multifunctional ethylenically unsaturated monomer is
 25 a fluorene-containing multifunctional ethylenically unsaturated monomer. Such monomer may comprise a major portion having the following general structure:



- wherein each Q is independently O or S. L is a divalent linking group. L may independently
 comprise a branched or linear C₂-C₁₂ alkylene group and n ranges from 0 to 10. L preferably
 30 comprises a branched or linear C₂-C₆ alkylene group. More preferably L is C₂ or C₃ and n is 0, 1,
 2 or 3. The carbon chain of the alkylene linking group may optionally be substituted with one or

5 more hydroxy groups. For example L may be $-\text{CH}_2\text{CH}(\text{OH})\text{CH}_2-$. Typically, the linking groups are the same. R1 is independently hydrogen or methyl.

One commercially available fluorene-containing multifunctional ethylenically unsaturated monomer is 9,9-bis[4-(2-acryloyloxyethoxy)phenyl]fluorene (NK Ester A-BPEF), available from Shin-Nakamura. The structure of this monomer is shown as follows:



10 In some embodiments, the (e.g. aromatic) ethylenically unsaturated (e.g. free-radically polymerizable) monomer has a specified hydrophilic-lipophilic balance ("HLB"). Although various methods have been described for determining the HLB of a compound, as used herein, HLB refers to the value obtained by the Griffin's method (See Griffin WC: "Calculation of HLB Values of Non-Ionic Surfactants," Journal of the Society of Cosmetic Chemists 5 (1954): 259). The computations were conducted utilizing the software program Molecular Modeling Pro Plus from Norgwyn Montgomery Software, Inc. (North Wales, PA).

20 According to Griffin's method:

$$HLB = 20 * Mh / M$$

where Mh is the molecular mass of the hydrophilic portion of the molecule, and M is the molecular mass of the whole molecule. This computation provides a numerical result on a scale of 0 to 20, wherein "0" is highly lipophilic.

25 In some embodiments, the (e.g. aromatic) ethylenically unsaturated monomer has a hydrophilic-lipophilic balance (HLB) of greater than 3.6. The HLB is typically at least 3.7, 3.8, 3.9, or 4.0. The HLB of the ethylenically unsaturated monomer is typically no greater than 7.3. When the HLB of the ethylenically unsaturated monomer is within this range, inclusion of the ethylenically unsaturated monomer does not increase the haze of the adhesive composition.

30 In some embodiments, the (e.g. aromatic) ethylenically unsaturated (e.g. free-radically polymerizable) monomer has a specified octanol/water partition coefficient (Log P). Although various methods have been described for determining the Log P of a compound, as used herein, Log P refers to the value obtained by the Moriguchi method (See Moriguchi, I; Hirono, S; Qian, L.; Nakagome, I.; and Matsushita, Y; Chemical and Pharmaceutical Bulletin, 40 (1992): 127).). The computations were conducted utilizing the software program Molecular Modeling Pro Plus from Norgwyn Montgomery Software, Inc. (North Wales, PA).

5 Log P is defined as the partitioning of the concentrations of a compound in octanol versus water:

$$\text{Log P} = \text{Log} ([\text{compound}]_{\text{octanol}} / [\text{compound}]_{\text{water}})$$

10 Higher values of Log P are more hydrophobic, while lower values of Log P are more hydrophilic. The Moriguchi method predicts Log P via a correlation developed employing over 1200 organic molecules having a wide variety of structures.

 In some embodiments, the (e.g. aromatic) ethylenically unsaturated monomer has a Log P of at least 1.8. The Log P is typically no greater than 6.0, 5.5, 5.0, 4.5, or 4.0. When the Log P of
15 the ethylenically unsaturated monomer is within this range, inclusion of the ethylenically unsaturated monomer does not increase the haze of the adhesive composition.

 In some embodiments, the ethylenically unsaturated monomer(s) are present as an (e.g. uncured) ethylenically unsaturated monomer at the time the (e.g. adhesive) composition is applied to a substrate. In some embodiments, the ethylenically unsaturated monomer(s) are present as an
20 (e.g. uncured) ethylenically unsaturated monomer after utilizing the (e.g. adhesive) composition is applied to a substrate. In some embodiments, the ethylenically unsaturated monomer is present as an (e.g. uncured or partially cured) ethylenically unsaturated monomer at the time the (e.g. adhesive) composition is applied to a substrate, yet the ethylenically unsaturated monomer is cured or in other words (e.g. completely) polymerized by exposure to heat or actinic radiation thereafter.
25 In yet another embodiment, the ethylenically unsaturated monomer is cured or in other words (e.g. completely) polymerized by exposure to heat or actinic radiation) before applying the (e.g. adhesive) composition to a substrate.

 When the ethylenically unsaturated monomer is partially cured, some of the monomer is polymerized and some ethylenically unsaturated monomer remains present in the composition.
30 When the ethylenically unsaturated monomer is completely cured, substantially all the monomer is polymerized.

 In some embodiments, the (e.g. adhesive) composition further comprises a polyisobutylene polymer that is not a styrene-isobutylene block copolymer. Such polyisobutylene polymers may be homopolymers and/or copolymers. Unless specified otherwise, as used herein
35 “polyisobutylene polymer” refers to both the homopolymer and the copolymer.

 In some embodiments, the polyisobutylene polymer comprises at least 90, 91, 92, 93, 94, 95, 96, 97, 98, or 99 mole-% of polymerized units of isobutylene. In other embodiments, the polyisobutylene polymer component comprises a polyisobutylene copolymer that comprises at least 50, 55 or 60 mole-% of polymerized units of isobutylene. In some embodiments, the

5 copolymer further comprises polymerized units derived from 1-butene and/or 2-butene. The polymerized units derived from 1-butene and/or 2-butene are typically present in an amount of at least 1, 5, 10, 15 or 20 mole-% ranging up to 30, 35, 40, 45 or 50 wt.-% of the polyisobutylene copolymer. Polyisobutylene copolymers further comprising polymerized units derived from 1-butene and/or 2-butene may be characterized as “polybutene”.

10 The composition may contain at least two polyisobutylene polymers where the first polyisobutylene polymer comprises a higher concentration of polymerized units derived from 1-butene and/or 2-butene than the second polyisobutylene polymer.

Other examples of polyisobutylene copolymers include copolymers of isobutylene and isoprene, copolymers of isobutylene and butadiene, and halogenated butyl rubbers obtained by
15 brominating or chlorinating these copolymers. However, the polyisobutylene copolymers can be free of halogenated butyl rubbers, the halogen (e.g. chloride, bromide) content being less than 1, 0.5, 0.25, 0.1, 0.01, or 0.001 mole percent of the polyisobutylene polymer.

The polyisobutylene copolymer typically does not contain a structural unit derived from styrene. Further, the polyisobutylene copolymers are typically random copolymers. Such
20 characteristic(s) distinguish polyisobutylene copolymer from the styrene-isobutylene block copolymer.

Thus, depending on the selection of polyisobutylene polymer(s), the polyisobutylene polymer component comprises at least 50, 55, 60, 65, 70, 75, 80, 85, 90, 95 wt.-% or greater of polymerized units of polyisobutylene.

25 Polyisobutylene polymer(s) can contain a trace amount of C8-C28 oligomers. The concentration of such is generally less than 0.15, 0.10, or 0.05 wt.-% based on the total weight of the polyisobutylene polymer.

It is appreciated that the polyisobutylene polymer(s) may have a very small concentration of reactive double bonds or other functional groups that are residual of the polymerization method
30 of making the polyisobutylene polymer. The concentration of such reactive double bonds or other functional groups is typically less than 5, 4, 3, or 2 mole %.

Polyisobutylene polymer(s) typically have a density of 0.92 g/cc. However, depending on the content of 1-butene and/or 2-butene and/or other alkene comonomer(s), the density may be 0.91 or lower. Further, the glass transition temperature of such polymers is typically -64°C to -
35 65°C as measured by Differential Scanning Calorimetry (DSC). Polyisobutylene polymer(s) typically cold flow at room temperature.

Polyisobutylene polymers are commercially available from several manufacturers. Homopolymers are commercially available, for example, under the trade designation OPPANOL (e.g., OPPANOL B12, B15, B30, B50, B80, B100, B150, and B200) from BASF Corp. (Florham

5 Park, N.J.). These polymers often have a weight average molecular weight in the range of about 40,000 to 1,000,000 g/mole or greater. Still other polyisobutylene polymers are commercially available in a wide range of molecular weights from United Chemical Products (UCP) of St. Petersburg, Russia; Exxon Chemical Company as the trade designation VISTANEXTM; and B.F. Goodrich as the trade designation "Hycar".

10 The polyisobutylene polymer has an average weight average molecular weight (Mw) ranging from 15,000 g/mole to 500,000; 1,000,000; 1,500,000; 2,000,000 or 2,500,000 g/mole. As used herein, all weight-average molecular weights are based on Gel Permeation Chromatography (GPC) utilizing polystyrene standards, per the test method described in the examples.

In some embodiments, the polyisobutylene polymer has a weight average molecular weight of at least 25,000; 30,000; 35,000; 40,000; 45,000; or 50,000 g/mole. In some
15 embodiments, the polyisobutylene polymer component has a weight average molecular weight of no greater than 300,000; 250,000; 200,000; 150,000; or 100,000 g/mole. Polyisobutylene polymers in this molecular weight ranges may be characterized as having an intermediate molecular weight. Intermediate molecular weight polyisobutylene homopolymers are also commercially available
20 from BASF (e.g., OPPANOL B10 and OPPANOL B15).

In some embodiments, the (e.g. adhesive) composition comprises a single polyisobutylene polymer. In other embodiments, the adhesive comprises a blend of two or more polyisobutylene polymers, wherein each polyisobutylene polymer has a different weight average molecular weight (Mw). For example, in some embodiments, the composition comprises a blend of a low molecular
25 weight polyisobutylene polymer (i.e. Mw is less than 15,000 g/mole) and an intermediate molecular weight polyisobutylene polymer. In other embodiments, the composition comprises a blend of a higher molecular weight polyisobutylene polymer (i.e. Mw greater than 300,000 g/mole) and an intermediate molecular weight polyisobutylene polymer. In yet another embodiment, the composition comprises a blend of a higher molecular weight polyisobutylene
30 polymer (i.e. Mw greater than 300,000 g/mole) and a lower molecular weight polyisobutylene polymer (i.e. Mw is less than 15,000 g/mole).

When the composition comprises two or more polyisobutylene polymers, the average weight average molecular weight of the component can be approximated by the summation of the average molecular weight of each polyisobutylene polymer multiplied by the weight fraction of
35 each polyisobutylene polymer within the polyisobutylene component. For example, if the polyisobutylene component contains 75 wt.-% of a first polyisobutylene polymer having a weight average molecular weight of 75,000 and 25 wt.-% of a second polyisobutylene polymer having a weight average molecular weight of 950 g/mole, the average weight average molecular weight can be approximated as $75,000 \times 0.75 + 950 \times 0.25 = 56,488$ g/mole.

5 In some embodiments, the (e.g. adhesive) composition comprises one or more low molecular weight polyisobutylene polymers having a weight average molecular weight less than 15,000 g/mole. The low molecular weight polyisobutylene polymers typically have a weight average molecular weight of at least 100, 200, 300, 400, or 500 g/mole. In some embodiments, the weight average molecular weight is less than 15,000; 10,000; 5,000; 4,000; 3,000; 2,000; or 1,000
10 g/mol. Such polyisobutylene polymers may comprise a higher concentration of polymerized units derived from 1-butene and/or 2-butene, as previously described. Thus, the density of the low molecular weight polyisobutylene polymers can be less than 0.92, 0.91, 0.90 g/cc, and may be for example 0.89 g/cc. Exemplary low molecular weight polyisobutylene (also referred to as polybutene) polymers are commercially available from Dowpol Chemical, Shanghai, China.

15 In some embodiments, the adhesive composition comprises at least 1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19 or 20 wt.-% of polyisobutylene polymer component. In some embodiments, the adhesive composition comprises no greater than 65, 60, 55, 50, 45, 40, 35, or 30 wt.-% of polyisobutylene polymer component.

The polyisobutylene polymer provides the desired water vapor transmission rate (WVTR)
20 properties. In some embodiments, the WVTR of a 50 micron layer of the composition is less than 100, 75, or 50 grams/square meter/day (g/sq.m/day) at 40°C and 100% relative humidity. In some embodiments, the WVTR of a 50 micron layer is less than 45, 40, 35, 30, 25, 20, 15, or 10 grams/square meter/day (g/sq.m/day) at 40°C and 100% relative humidity. In some embodiments, the WVTR can be less than 2, 1.5, 1, 0.5, 0.2, 0.25, 0.3, 0.35, or 0.4 g/sq.m/day per micron
25 thickness of (e.g. adhesive) composition.

In order for the adhesive composition to provide a desirably high creep compliance the amount of styrene-isobutylene block copolymer is greater than the amount of polyisobutylene polymer. The creep compliance is preferably less than 1.5×10^{-4} 1/Pa (i.e. 1.5 E-04 1/Pa) at 25°C, measured 287 seconds after a stress of 8,000 Pa was applied for 5 minutes as determined by the
30 test method described in the examples. The lower the creep compliance, the greater the cohesive strength. In some embodiments, the creep compliance is less than 1 E-04 1/Pa, or less than 9 E-05 1/Pa, or less than 8 E-05 1/Pa, or less than 7 E-05 1/Pa, or less than 6 E-05 1/Pa, or less than 5 E-05 1/Pa, or less than 4 E-05 1/Pa, or less than 3 E-05 1/Pa, or less than 2 E-05 1/Pa, or less than 1 E-05 1/Pa. The creep compliance is typically at least 1 E-08 1/Pa, 1 E-07 1/Pa, or 1 E-06 1/Pa.

35 In some embodiments, the weight ratio of styrene-isobutylene block copolymer to polyisobutylene polymer component is at least 2.2:1 and in some embodiments at least 2.3:1, 2.4:1, 2.5:1, 2.6:1, 2.7:1, 2.8:1, 2.9:1, or 3:1. When the polyisobutylene is an intermediate molecular weight polymer as subsequently described the weight ratio is typically no greater than 5:1 or 4.5:1, or 4:1. However, when the polyisobutylene is a low molecular weight polyisobutylene polymer in

5 combination with an intermediate or high molecular weight polymer as previously described, the weight ratio may be higher and can be at least 5:1, 5.5:1, 6:1, 6.5:1, 7:1, 7.5:1, 8:1, 8.5:1, 9:1, 9.5:1, or 10:1. In some embodiments, the weight ratio of styrene-isobutylene block copolymer to polyisobutylene polymer component is no greater than 20:1, 19:1, 18:1, 17:1, 16:1 or 15:1.

10 The (e.g. adhesive) composition may optionally comprise one or more additives such as tackifiers, plasticizers (e.g. oils, polymers that are liquids at 25°C), antioxidants (e.g., hindered phenol compounds, phosphoric esters, or derivatives thereof), ultraviolet light absorber (e.g., benzotriazole, oxazolic acid amide, benzophenone, or derivatives thereof), in-process stabilizers, anti-corrosives, passivation agents, light stabilizers, processing assistants, elastomeric polymers (e.g. other block copolymers), scavenger fillers, nanoscale fillers, transparent fillers, desiccants, 15 crosslinkers, pigments, organic solvents, etc. The total concentration of such additives ranges from 0 – 60 wt.-% of the total (e.g. adhesive) composition.

The adhesive composition optionally comprises a tackifier. In some embodiments the adhesive composition comprises a tackifier. The concentration of tackifier can vary depending on the intended (e.g. pressure sensitive) adhesive composition. In some embodiments, the amount of 20 tackifier is at least 1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15 wt.-%. The maximum amount of tackifier is typically no greater than 60, 55, 50, 45, 40, 35, or 30 wt.-%. Increasing the (e.g. solid at 25°C) tackifier concentration typically raises the T_g of the adhesive. In other embodiments, the adhesive composition comprises little or no tackifier. Thus, the concentration of tackifier is less than 5, 4, 3, 2, 1, 0.5, or 0.1 wt.-%.

25 The tackifier can have any suitable softening temperature or softening point. The softening temperature is often less than 200°C, less than 180°C, less than 160°C, less than 150°C, less than 125°C, or less than 120°C. In applications that tend to generate heat, however, the tackifier is often selected to have a softening point of at least 75°C. Such a softening point helps minimize separation of the tackifier from the rest of the adhesive composition when the adhesive 30 composition is subjected to heat such as from an electronic device or component. The softening temperature is often selected to be at least 80°C, at least 85°C, at least 90°C, or at least 95°C. In applications that do not generate heat, however, the tackifier can have a softening point less than 75°C.

Suitable tackifiers include hydrocarbon resins and hydrogenated hydrocarbon resins, e.g., 35 hydrogenated cycloaliphatic resins, hydrogenated aromatic resins, or combinations thereof. Suitable tackifiers are commercially available and include, e.g., those available under the trade designation ARKON (e.g., ARKON P or ARKON M) from Arakawa Chemical Industries Co., Ltd. (Osaka, Japan); those available under the trade designation ESCOREZ (e.g., ESCOREZ 1315, 1310LC, 1304, 5300, 5320, 5340, 5380, 5400, 5415, 5600, 5615, 5637, and 5690) from Exxon

5 Mobil Corporation, Houston, TX; and those available under the trade designation REGALREZ (e.g., REGALREZ 1085, 1094, 1126, 1139, 3102, and 6108) from Eastman Chemical, Kingsport, TN. The above tackifiers may be characterized as midblock tackifiers, being compatible with the isobutylene block of the styrene-isobutylene block copolymer as well as the polyisobutylene polymer. In some embodiments, the adhesive may comprise an endblock aromatic tackifier that is
10 compatible with the styrene block of the block copolymer.

In some embodiments, the (e.g. adhesive) composition further comprise at least one free-radical initiator.

Useful photoinitiators include those known as useful for photocuring free-radically polyfunctional (meth)acrylates. Exemplary photoinitiators include benzoin and its derivatives
15 such as alpha-methylbenzoin; alpha-phenylbenzoin; alpha-allylbenzoin; alpha benzylbenzoin; benzoin ethers such as benzil dimethyl ketal (e.g., 2,2-Dimethoxy-2-phenylacetophenone obtained under the trade designation of "OMNIRAD BDK" from IGM Resins USA Inc., St. Charles, IL), benzoin methyl ether, benzoin ethyl ether, benzoin n-butyl ether; acetophenone and its derivatives such as 2-hydroxy-2-methyl-1-phenyl-1-propanone (e.g., available under the trade designation
20 OMNIRAD 1173 from IGM Resins USA Inc., St. Charles, IL) and 1-hydroxycyclohexyl phenyl ketone (e.g., available under the trade designation OMNIRAD 184 from IGM Resins USA Inc., St. Charles, IL); 2-methyl-1-[4-(methylthio)phenyl]-2-(4-morpholinyl)-1-propanone (e.g., available under the trade designation OMNIRAD 907 from IGM Resins USA Inc., St. Charles, IL); 2-benzyl-2-(dimethylamino)-1-[4-(4-morpholinyl)phenyl]-1-butanone (e.g., available under the trade
25 designation OMNIRAD 369 from IGM Resins USA Inc., St. Charles, IL) and phosphine oxide derivatives such as ethyl-2,4,6-trimethylbenzoylphenyl phosphinate (e.g. available under the trade designation TPO-L from IGM Resins USA Inc., St. Charles, IL), and bis-(2,4,6-trimethylbenzoyl)-phenylphosphineoxide (e.g., available under the trade designation OMNIRAD 819 from IGM Resins USA Inc., St. Charles, IL).

30 Other useful photoinitiators include, for example, pivaloin ethyl ether, anisoil ethyl ether, anthraquinones (e.g., anthraquinone, 2-ethylanthraquinone, 1-chloroanthraquinone, 1,4-dimethylanthraquinone, 1-methoxyanthraquinone, or benzanthraquinone), halomethyltriazines, benzophenone and its derivatives, iodonium salts and sulfonium salts, titanium complexes such as bis(eta⁵-2,4-cyclopentadien-1-yl)-bis[2,6-difluoro-3-(1H-pyrrol-1-yl) phenyl]titanium (e.g.,
35 available under the trade designation CGI 784DC from BASF, Florham Park, NJ); halomethyl-nitrobenzenes (e.g., 4-bromomethylnitrobenzene), and combinations of photoinitiators where one component is a mono- or bis-acylphosphine oxide (e.g., available under the trade designations IRGACURE 1700, IRGACURE 1800, and IRGACURE 1850 from BASF, Florham Park, NJ, and under the trade designation OMNIRAD 4265 from IGM Resins USA Inc., St. Charles, IL); and

5 halomethyltriazine-based photoinitiators such as are 2-[2-(4-methoxy-phenyl)-vinyl]-4,6-bis-trichloromethyl [1,3,5]triazine, 2-(4-methoxy-phenyl)-4,6-bis-trichloromethyl [1,3,5]triazine, 2-(3,4-dimethoxyphenyl)-4,6-bis-trichloromethyl [1,3,5]triazine, and 2-methyl-4,6-bis-trichloromethyl [1,3,5] triazine.

10 In some embodiments, a thermal free-radical initiator may be used. Suitable classes of thermal, free-radical initiators include, but are not limited to thermally labile azo compounds and peroxides. Non-limiting examples of thermally labile azo compounds include those under the trade designation VAZO from the Chemours Company (Wilmington, DE), such as 2,2'-azobisisobutyronitrile, 2,2'-azobis-2-methylbutyronitrile, 2,2'- azobis-2-methylvaleronitrile, 2,2'-azobis-2,3-dimethylbutyronitrile, and combinations thereof and the like. Non-limiting examples of
15 peroxides include, but are not limited, to organic peroxides under the trade designation LUPEROX available from Arkema Inc. (Philadelphia, PA), and include cumene hydroperoxide, methyl ethyl ketone peroxide, benzoyl peroxide, di-t-butyl peroxide, di-t-amyl peroxide, t-butyl-cumyl peroxide, dicumyl peroxide, t-butyl hydroperoxide, t-butyl peracetate, di-n-propyl peroxydicarbonate and combinations thereof and the like.

20 Generally, the initiator(s) are used in amounts of 0.01 to 10 parts by weight, more typically 0.1 to 2.0, parts by weight relative to 100 parts by weight of the total composition.

In some embodiments, the (e.g. adhesive) composition comprises an ultraviolet absorber (UVA) (e.g., benzotriazole) at a concentration of at least 1, 1.5, 2, 2.5, 3, 3.5, 4, 4.5, or 5 wt.-% of the adhesive composition. The concentration of the ultraviolet absorber (e.g., benzotriazole) is
25 typically no greater than 15, 14, 13, 12, or 10 wt.-%. In some embodiments, the inclusion of the ultraviolet absorbent (e.g., benzotriazole) can reduce the transmission (e.g. of a 50 micron thick layer) at 380 and 385 nm to less than 20, 15, 10, 9, 8, 7, 6, 5, 4, 3, or 2%. In other words, the transmission can be less than 0.4%, 0.3%, 0.2%, 0.1%, 0.09%, 0.08%, 0.07%, 0.06%, 0.05% or 0.04% per micron thickness of (e.g. adhesive) composition. It has been found that relatively high
30 concentrations of UVAs can be included without increasing yellowing, as indicated by the b* value, as measured according to the test method described in the example. In some embodiments, the b* values of a 50 micron thick layer of the (e.g. adhesive) composition is preferably less than 2, 1.5, 1 or 0.5 initially and after aging at 66°C and 80% relative humidity for 72 hours. In other words the b* values can be less than 0.04, 0.03, 0.02, or 0.01 per micron thickness of (e.g.
35 adhesive) composition.

When it is desired for the (e.g. adhesive) composition to be transparent, the composition is typically free of fillers having a particle size greater than 100 nm that can detract from the transparency of the adhesive composition. In this embodiment, the total amount of filler of the composition is no greater than 10, 9, 8, 7, 6, 5, 4, 3, or 2 wt.-% solids of the adhesive composition.

5 In some favored embodiments, the composition comprises no greater than 1, 0.5, 0.1, or 0.05 wt.-% of filler.

However, in other embodiments, the (e.g. adhesive) composition may comprise higher amounts of inorganic oxide filler such as fumed silica.

10 In some embodiments, the compositions are prepared by dissolving the polyisobutylene polymer, styrene-isobutylene block copolymer, and other optional components in an organic solvent. Suitable solvents include for example alkanes, ethyl acetate, toluene and tetrahydrofuran. In other embodiments, the compositions may be characterized as hot-melts. Such (e.g. adhesive) composition are typically applied from the melt and are solvent-free. Alternatively, a solidified hot melt or dried solvent based (e.g. adhesive) composition may be applied to a substrate or
15 between substrates. The (e.g. adhesive) composition may be heated after application to the substrate.

The thickness of the (e.g. adhesive) composition layer is typically at least 10, 15, 20, or 25 microns (1 mil) ranging up to 500 microns (20 mils) thickness. In some embodiments, the thickness of the (e.g. adhesive) composition layer is no greater than 400, 300, 200, or 100 microns.
20 The (e.g. adhesive) composition can be coated in single or multiple layers. The layers may be continuous or discontinuous.

In some methods of bonding or methods of making an article, the method comprises applying the composition to a substrate; and curing the (meth)acryl and/or vinyl ether groups of the ethylenically unsaturated monomer. The composition typically comprises a free-radical
25 thermal initiator or photoinitiator, as known in the art.

The composition comprising photoinitiator may be irradiated with UV radiation having a UVA maximum in the wavelength range of 280 to 425 nanometers to polymerize the ethylenically unsaturated monomer(s). UV light sources can be of various types. Low light intensity sources, such as blacklights, generally provide intensities ranging from 0.1 or 0.5 mW/cm² (milliwatts per
30 square centimeter) to 10 mW/cm² (as measured in accordance with procedures approved by the United States National Institute of Standards and Technology as, for example, with a UVIMAP UM 365 L-S radiometer manufactured by Electronic Instrumentation & Technology, Inc., in Sterling, VA). High light intensity sources generally provide intensities greater than 10, 15, or 20 mW/cm² ranging up to 450 mW/cm² or greater. In some embodiments, high intensity light sources
35 provide intensities up to 500, 600, 700, 800, 900 or 1000 mW/cm². UV light to polymerize the ethylenically unsaturated monomer(s) can be provided by various light sources such as light emitting diodes (LEDs), blacklights, medium pressure mercury lamps, etc. or a combination thereof. The monomer component(s) can also be polymerized with higher intensity light sources as available from Fusion UV Systems Inc. The UV exposure time for polymerization and curing can

5 vary depending on the intensity of the light source(s) used. For example, complete curing with a low intensity light source can be accomplished with an exposure time ranging from about 30 to 300 seconds; whereas complete curing with a high intensity light source can be accomplished with shorter exposure time ranging from about 5 to 20 seconds. Partial curing with a high intensity light source can typically be accomplished with exposure times ranging from about 2 seconds to
10 about 5 or 10 seconds.

In some favored embodiments, the composition is a pressure sensitive adhesive.

Pressure sensitive adhesives are often characterized as having a storage modulus (G') at the application temperature, typically room temperature (e.g. 25°C), of less than 3×10^5 Pa (0.3 MPa) when measured at a frequency of 1 Hz. As used herein, storage modulus (G') refers to the
15 value obtained utilizing Dynamic Mechanical Analysis (DMA) per the test method described in the examples. In some embodiments, the pressure sensitive adhesive composition has a storage modulus of less than 2×10^5 Pa, 1×10^5 Pa, 9×10^4 Pa, 8×10^4 Pa, 7×10^4 Pa, 6×10^4 Pa, 5×10^4 Pa, 4×10^4 Pa, or 3×10^4 Pa. In some embodiments, the composition has a storage modulus (G') of at least 2.0×10^4 Pa or 2.5×10^4 Pa.

20 In some embodiments, curing the ethylenically unsaturated monomer can increase the storage modulus by at least 10,000; 20,000; 30,000; 40,000; 50,000; 60,000, or 70,000 Pa.

Pressure sensitive adhesives are often characterized as having a glass transition temperature “T_g” below 25°C; whereas other adhesives may have a T_g of 25°C or greater, typically ranging up to 50°C. As used herein, T_g refers to the value obtained utilizing DMA per
25 the test method described in the examples. In some embodiments, the pressure sensitive adhesive composition has a T_g no greater than 20°C, 15°C, 10°C, 5°C, 0°C, or -5°C. The T_g of the pressure sensitive adhesive is typically at least -40°C, -35°C, -30°C, -25°C, or -20°C.

Pressure sensitive adhesive are often characterized as having adequate adhesion. In some
30 embodiments, the peel adhesion (e.g. to stainless steel), as measured according to the test method described in the examples, is at least 0.1, 0.5, 1, 2, 3, 4, or 5 N/dm ranging up to for example 15, 16, 17, 18, 19, or 20 N/dm.

In some embodiments, curing the ethylenically unsaturated monomer can reduce the peel adhesion to stainless steel by 1 or 2 N/dm.

35 As used herein, the term “adhesive” refers to a pressure sensitive adhesive or an adhesive that is not a pressure sensitive adhesive, unless specified otherwise.

The adhesive composition may be coated upon a variety of flexible and inflexible backing materials using conventional coating techniques to produce a single coated or double coated adhesive tape, and adhesive transfer tapes. Generally, adhesive transfer tapes comprise a layer of

5 adhesive disposed on a release liner. Such products can be formed by applying (e.g., coating, casting, or extruding) the adhesive onto a release liner, and drying the adhesive if an organic solvent is present.

The tape may further comprise a release material or release liner. For example, in the case of a single-coated tape, the side of the backing surface opposite that where the adhesive is disposed is typically coated with a suitable release material. Release materials are known and include
10 materials such as, for example, silicone, polyethylene, polycarbamate, polyacrylics, and the like. For double coated tapes, a second layer of adhesive is disposed on the opposing surface of the backing surface. The second layer may also comprises the adhesive composition as described herein or a different adhesive composition.

15 Flexible substrates are defined herein as any material which is conventionally utilized as a tape backing or may be of any other flexible material. Examples include, but are not limited to polymeric films, woven or nonwoven fabrics (e.g. scrim); metal foils, foams (e.g., polyacrylic, polyethylene, polyurethane, neoprene), and combinations thereof (e.g. metalized polymeric film). Polymeric film include for example polypropylene (e.g. biaxially oriented), polyethylene (e.g. high
20 density or low density), polyvinyl chloride, polyurethane, polyester (polyethylene terephthalate), polycarbonate, polymethyl(meth)acrylate (PMMA), polyvinylbutyral, polyimide, polyamide, fluoropolymer, cellulose acetate, cellulose triacetate, and ethyl cellulose. The woven or nonwoven fabric may comprise fibers or filaments of synthetic or natural materials such as cellulose (e.g. tissue), cotton, nylon, rayon, glass, ceramic materials, and the like.

25 A substrate may be bonded by the adhesive composition or (e.g. transfer, single-sided, or double-coated tape described herein. The substrate may comprise the same materials as just described for the backing.

One method of bonding comprises providing a first substrate and contacting a surface of the first substrate with the (e.g. pressure sensitive) adhesive composition. In this embodiment, the
30 opposing surface of the adhesive is typically temporarily covered by a release liner.

In other embodiments, the method further comprises contacting the opposing surface of the (e.g. pressure sensitive) adhesive (e.g. layer) to a second substrate. The first and second substrate may be comprised of various materials as previously described such as metal, an inorganic material (e.g. glass), an organic polymeric material, or a combination thereof.

35 In some methods of bonding, the substrate, (e.g. pressure sensitive) adhesive composition, or combination thereof may be heated to reduce the storage modulus (G') and thereby increase the bond strength formation. The substrate and/or (e.g. pressure sensitive) adhesive may be heated to a temperature up to 30, or 35, or 40, or 45, or 50, or 55, or 60, or 65 or 70°C. In some embodiments, the substrate(s) together with the adhesive bonded to the substrate(s) by means of

5 the initial peel adhesion strength at ambient temperature (e.g. 25°C) is heated in an oven to the desired temperature. In other embodiments, the substrate and/or (e.g. pressure sensitive) adhesive is heated by means of a hot air gun.

In some embodiments, the composition described herein is optically clear. Thus, certain articles can be laminates that include an optically clear substrate (e.g., an optical substrate such as
10 an optical film) and an optically clear adhesive layer or coating disposed on at least one major surface of the optically clear substrate. The laminates can further include a second substrate permanently or temporarily attached to the pressure-sensitive adhesive layer and with the pressure-sensitive adhesive layer being positioned between the optically clear substrate and the second substrate.

15 In one embodiment, the laminate may be a removable or permanent surface protection film. In some embodiments, the tapes and protective films can be utilized for (e.g. illuminated) displays that can be incorporated into household appliances, automobiles, computers (e.g. tablets), and various hand-held devices (e.g. phones). In other embodiments, the adhesive coated film may be suitable for architectural applications, glazing (e.g., windows and windshields), and graphic
20 film applications.

In some embodiments, the (e.g. adhesive) composition and optically clear substrate (e.g. transparent film) have a transmission as measured according to the test method described in the examples of visible light (410 nm) of at least 90 percent for a layer of adhesive having a thickness of 50 micrometers. In some embodiments, the transmission is at least 91, 92, 93, 94, 95, 96, 97,
25 98, or 99%.

In some example laminates in which an optically clear pressure-sensitive adhesive layer is positioned between two substrates, at least one of the substrates is an optical film, a display unit (e.g., liquid crystal displays (LCDs), organic light emitting displays (OLEDs), a touch sensor, or a lens. Optical films intentionally enhance, manipulate, control, maintain, transmit, reflect, refract,
30 absorb, retard, or otherwise alter light that impinges upon a surface of the optical film. Optical films included in the laminates include classes of material that have optical functions, such as polarizers, interference polarizers, reflective polarizers, diffusers, colored optical films, mirrors, louvered optical film, light control films, transparent sheets, brightness enhancement film, anti-glare, and anti-reflective films, and the like. Optical films for the provided laminates can also
35 include retarder plates such as quarter-wave and half-wave phase retardation optical elements. Other optically clear films can include clear plastics (such as polyester, cyclic olefin copolymer, clear polyimide, polycarbonate, or polymethylmethacrylate), anti-splinter films, and electromagnetic interference filters. Some of these films may also be used as substrates for ITO (i.e., indium tin oxide) coating or patterning, such as use those used for the fabrication of touch

5 sensors. The low water uptake and WVTR of the adhesives described herein provide a stable, low dielectric constant OCA which can be very advantageous for use in touch sensor applications, both to protect the sensor and integrating conductors from the environment and corrosion, and also to minimize electronic noise communication with the sensor. In some embodiments, the (e.g. pressure sensitive) adhesive and (e.g. transfer and double-coated) tapes described herein are
10 suitable for bonding internal components or external components of an optical elements such as illuminated display devices such as liquid crystal displays ("LCDs") and light emitting diode ("LEDs") displays such as cell phones (including Smart phones), wearable (e.g. wrist) devices, car navigation systems, global positioning systems, depth finders, computer monitors, notebook and tablet computer displays. Other types of optical elements include projection (e.g. lens)
15 components, photonic components, and polarizing beam splitters.

In some embodiments, the composition is suitable for use as an encapsulating composition for use in an electronic device as described for example in US2009/0026924; incorporated herein by reference.

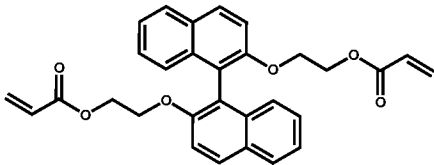
Specifically, the (e.g. pressure sensitive) adhesive can be used as a sealing member for
20 electronic devices, for example, organic devices such as an organic transistor, an organic memory, and an organic EL element; liquid crystal displays; electronic paper; thin film transistors; electrochromic devices; electrochemical light-emitting devices; touch panels; solar batteries; thermoelectric conversion devices; piezoelectric conversion devices; electric storage devices; and the like.

EXAMPLES

Unless otherwise noted, all parts, percentages, ratios, etc. in the Examples and the rest of the specification are by weight. Unless otherwise indicated, all other reagents were obtained, or are available from fine chemical vendors such as Sigma-Aldrich Company, St. Louis, Missouri, or
30 may be synthesized by known methods. Tables 1A and 1B (below) lists materials used in the examples and their sources.

5

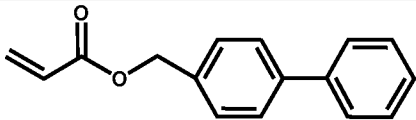
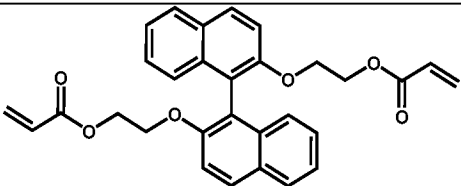
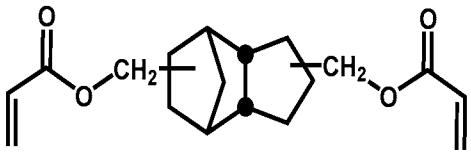
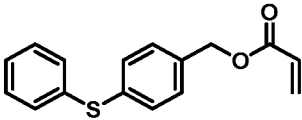
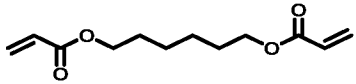
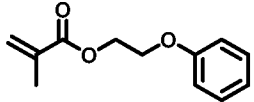
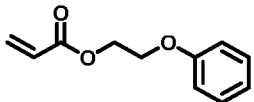
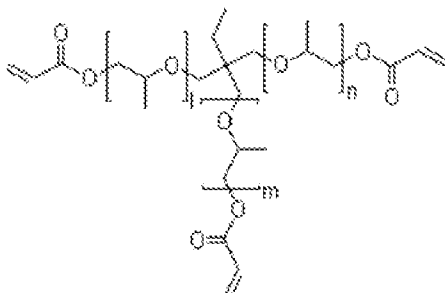
TABLE 1A. Materials List

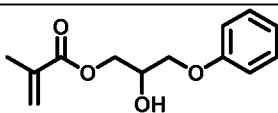
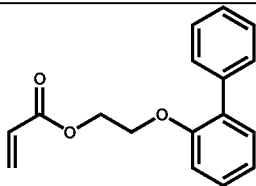
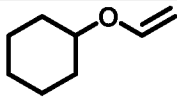
DESIGNATION	DESCRIPTION	SOURCE
OB15	Polyisobutylene (PIB) (molecular weight ~ 75 kg/mol) obtained under the trade designation OPPANOL B15	BASF Corporation, Florham Park, NJ, USA
OB10	Polyisobutylene (molecular weight ~ 50 kg/mol) obtained under the trade designation OPPANOL B10	BASF Corporation
SIBS 102T	Poly (Styrene-isobutylene-styrene) (SIBS), molecular weight about 100 kg/mol and 15% styrene obtained under the trade designation SIBSTAR 102T	Kaneka, Pasadena, TX, USA
SIBS 103T	Poly (Styrene-isobutylene-styrene) (SIBS)), molecular weight about 100 kg/mol and 30% styrene obtained under the trade designation SIBSTAR 103T	Kaneka
E5300	Cycloaliphatic hydrocarbon resin obtained under the trade designation ESCOREZ 5300	Exxonmobil, Houston, TX, USA
M1192H	Biphenylmethyl acrylate obtained under the trade designation MIRAMER M1192H	Miwon Specialty Chemical Co., Gyeonggi-do, South Korea
BNP-1	([1,1'-binaphthalene]-2,2'-diylbis(oxy))bis(ethane-2,1-diyl) diacrylate available as KAYARAD BNP-1 from Nippon Kayaku Co. Ltd. Tokyo, Japan 	Nippon Kayaku Co. Ltd., Tokyo, Japan
SR833S	Tricyclodecane dimethanol diacrylate obtained under the trade designation SR833 S	Sartomer, Exton, PA
PTPBA	Para-thiophenoxybenzylacrylate	Synthesis 1 of PCT/IB2017/058440

TPO-L	Trimethylbenzoylphenylphosphine oxide	BASF Corporation
RF22N	Release liner obtained under the trade designation RF 22N	SKC Haas, Cheonan-si, South Korea
RF02N	Release liner obtained under the trade designation RF 02N	SKC Haas
Toluene	Toluene (solvent)	EMD Millipore Corp., Billerica, MA, USA
2-EHA	2-Ethylhexyl acrylate	Sigma-Aldrich, St. Louis, MO, USA
IBOA	Isobornyl acrylate	Sartomer, Exton, PA, USA
HEA	2-Hydroxyethyl acrylate	BASF Corporation
D1173	Photoinitiator; 2-hydroxy-2-methyl-1-phenyl propan-1-one, obtained under the trade designation Darocur 1173	BASF Corporation
I651	Photoinitiator, 2,2-dimethoxy-2-phenylacetophenone, obtained under the trade designation IRGACURE 651	BASF Corporation
HDDA	Hexanedioldiacrylate	Sigma-Aldrich
SR340	2-phenoxyethyl methacrylate	Sartomer, Exton, PA, USA
PHPM	3-phenoxy-2-hydroxypropyl methacrylate	Polysciences Inc., Warrington, PA
SR339	2-phenoxyethyl acrylate	Sartomer, Exton, PA, USA
OPPEA	o-Phenylphenol acrylate	KPX Green chemical, Seoul Korea
CVE	Cyclohexyl vinyl ether	Sigma-Aldrich, Milwaukee, WI, USA
SR492	Propoxylated trimethylpropane triacrylate	Sartomer, Exton, PA, USA

5

TABLE 1B. Refractive index and structures of curable acrylates

DESIGNATION	RI (of uncured material)	Moriguchi Log P	HLB (hydrophobic lypophobic balance)	Structure
M1192H	1.598	3.3	4.5	
BNP-1	1.633	3.6	7.3	
SR833S	1.504	2.8	6.5	
PTPBA	1.604	3.8	4.0	
HDDA	1.456 ^a	2.0	9.2	
SR340	1.5109 ^c	2.1	5.6	
SR339	1.516 ^c	1.8	7.3	
SR492	1.459	1.6	10.5	 $l, m, \text{ and } n = 1$

PHPM	1.521	1.6	7.4	
OPPEA	1.578	3.0	5.7	
CVE	1.454 ^a	1.7	3.6	

- 5 ^a Obtained from Sigma Aldrich technical data sheet; ^b Obtained from BASF technical data sheet;
^c Obtained from Sartomer technical data sheet

Test Methods

Method for Determining Log P

- 10 Log water octanol partition coefficient was calculated by the Moriguchi method implemented in the software program Molecular Modeling Pro Plus, Version 6.2.6, Norgwyn Montgomery Software Inc. (North Wales, PA, USA)

Method for Determining HLB

- 15 HLB was calculated by Griffin's method implemented in the software program Molecular Modeling Pro Plus, Version 6.2.6, Norgwyn Montgomery Software Inc. (North Wales, PA, USA)

Method for Haze Measurement

- 20 Test specimens were prepared by cleaning the LCD (liquid crystal display) glass three times with IPA (isopropyl alcohol) and completely drying the surface with a KIMWIPE (KIMTECH by Kimberly-Clark, Irving, TX, USA). Each test specimen was cut to a size large enough to cover the entrance port. The clear liner was removed and the adhesive was laminated on the LCD glass with four passes of a small rubber hand roller. The sample should be free of visible distinct internal voids, particles, scratches, and blemishes. Then test sample was then placed in a
- 25 65°C, 90% relative humidity testing chamber. In 10 minutes, the other clear liner was removed and the haze was measured according to ASTM D 1003-92 (1992) against the background of the LCD glass with UltraScan Pro (Hunterlab, Reston, VA, USA) equipped with a visible light source.

5 *Method for Determination of the Water Vapor Transmission Rate (WVTR)*

Water Vapor Transmission Rate was measured according to ASTM F-1249 (1990). The sample area was 50 square centimeters (cm²). Samples were prepared by placing a 2 mil (0.05 mm) slab of adhesive between two porous polypropylene films (Example 2 of US 5,238,623). The prepared samples were then placed in the PERMATRAN-W Model 700 instrument (Mocon Inc.,
10 Brooklyn Park, MN, USA) for testing at 40 °C and 100% relative humidity gradient.

Method for Determining Refractive Index (RI)

The refractive indices (RI) of the samples were measured on a Metricon 2010/M (Metricon Corp, Melbourne, Australia). Samples were prepared by removing one release liner
15 from the adhesive transfer tapes (prepared as described below) and then bringing the sample into contact with the prism and exposing the sample to a 532 nanometers (nm) (green) laser. Three readings were collected per sample. The values reported are the average of the three measurements. The RI of polyisobutylene at 532 nm is 1.51. An increase of 0.001 is considered significant.

20

Method for Peel Adhesion Strength

Peel adhesion strength was measured at an angle of 180° using an IMASS SP-200 slip/peel tester (available from IMASS, Incorporated, Accord, MA) at a peel rate of 305 millimeters/minute (12 inches/minute). Stainless steel test panels measuring 25.4 centimeters by 12.7 centimeters (10
25 inches by 5 inches) were cleaned by wiping them with isopropanol using a lint-free tissue and allowing them to air dry for 30 minutes after which they were clamped to the test stage of the peel tester. Tape samples (prepared by coating a 50 micron thick PET film as described in CE-1) measuring approximately 1.3 centimeters by 20 centimeters (0.5 inches by 8 inches) were then applied to the cleaned test panels with the adhesive side in contact with the test panel. The tape
30 samples were then rolled over using a 2.0 kilogram (4.5 pound) rubber roller one time in each direction. The taped panels were stored and tested at 23°C and 50% relative humidity (RH). Testing was conducted 20 minutes after preparation. Three to five taped panels were evaluated and the average peel adhesion strength of the total number of panel tested was reported. Results were obtained in ounces/inch and converted to Newtons/decimeter (N/dm). In addition, it was noted if
35 any adhesive residue remained on the stainless steel panel after removal of the tape sample.

5 Method for Storage Modulus and Tan Delta as Determined by Dynamic Mechanical Analysis

Dynamic mechanical analysis (“DMA”) of adhesive samples was carried out using a rheometer (obtained from TA Instruments, New Castle, DE, under the trade designation “AR2000 PARALLEL PLATE RHEOMETER”) to characterize the physical properties of each sample as a function of temperature. For each sample, 50 micrometer thick sheets of the polymerized adhesive sample were laminated together to achieve a 1 mm thick slab. A circular punch with a diameter of 8 mm was used to cut a sample from this slab which was then centered between the 8 mm diameter parallel plates of the rheometer. The temperature was then scanned from -40°C to 120°C at a rate of 3°C/min. while the parallel plates were oscillated at a frequency of 1 Hz and a constant strain of 0.4%. Physical parameters of the material were recorded during the temperature ramp, including storage modulus (G') and tan delta at 150°C.

Examples

Example Set 1 (Choosing the base polymers)

COMPARATIVE EXAMPLE 1 (CE-1):

In CE-1, 8 grams (g) of OPPANOL B15, 2 g of ESCOREZ 5300, 1.8 g of M1192H, 0.2 g of SR833S, and 0.05 g of TPO-L were added in a glass vial with toluene to make a solution with 40% solids (Table 2). The vial was sealed and contents were mixed overnight. The solution was then coated on a 50 micrometer (μm) thick siliconized polyester release liner, RF22N (SKC Haas, Korea) using a knife coater with a gap of 6 mil (0.15 millimeters (mm)). The coated sample was placed in an oven at 70°C for 15 minutes. The coated sample was exposed to UV radiation: UVA of 2 Joules per centimeters squared (J/cm^2), UVB of 1.7 J/cm^2 , UVC of 0.5 J/cm^2 . The total dosage of UV radiation was 6.2 W/cm^2 of UVA, 1.8 W/cm^2 of UVB, and 0.6 W/cm^2 of UVC. The final film thickness was 1 mil (0.03 mm).

EXAMPLES 1 to 4 (EX-1 to EX-4):

Examples 1 to 4 were prepared similarly to CE-1, only using the components and amounts listed in Table 2. For each example, all components were added in a glass vial with toluene to make a solution with 40% solids. The vial was then sealed and contents were mixed overnight. The solutions were then individually coated according to the same coating procedure outlined in CE-1.

35 *Example Set 2 (Different amount of organic additives)*

COMPARATIVE EXAMPLE 2 (CE-2):

CE-2 was prepared similarly to CE-1, only using the components and amounts listed in Table 2. All components were added in a glass vial with toluene to make a solution with 40%

5 solids. The vial was then sealed and contents were mixed overnight. The solution was then coated on a 50µm thick siliconized polyester release liner, RF22N (SKC Haas, Korea) using a knife coater with a gap of 6 mil. The coated sample was placed in an oven at 70°C for 15 minutes. The final film thickness was 1 mil (0.03 mm).

10 EXAMPLES 5 to 7 (EX-5 to EX-7):

Examples 5 to 7 were prepared similarly to CE-1, only using the components and amounts listed in Table 2. For each example, all components were added in a glass vial with toluene to make a solution with 40% solids. The vial was then sealed and contents were mixed overnight. The solutions were then individually coated according to the same coating procedure outlined in CE-1.

15

Example Set 3 (Different organic additives)

COMPARATIVE EXAMPLE 3 (CE-3):

CE-3 was prepared similarly to CE-1, only using the components and amounts listed in Table 3. All components were added in a glass vial with toluene to make a solution with 40% solids. The vial was then sealed and contents were mixed overnight. The solution was then coated on a 50 µm thick siliconized polyester release liner, RF22N (SKC Haas, Korea) using a knife coater with a gap of 6 mil (0.15 mm). The coated sample was placed in an oven at 70°C for 15 minutes. The final film thickness was 1 mil (0.03 mm).

25 EXAMPLES 8 to 13 (EX-8 to EX-13):

Examples 8 to 13 were prepared similarly to CE-1, only using the components and amounts listed in Table 3. For each example, all components were added in a glass vial with toluene to make a solution with 40% solids. The vial was then sealed and contents were mixed overnight. The solutions were then individually coated according to the same coating procedure outlined in CE-1.

30

Example Set 4 (Effect of UV exposure)

EXAMPLE 14 (EX-14):

Example 14 was prepared similarly to CE-1, only using the components and amounts listed in Table 3. All components were added in a glass vial with toluene to make a solution with 40% solids. The vial was then sealed and contents were mixed overnight. The solution was then coated on a 50 µm thick siliconized polyester release liner, RF22N (SKC Haas, Korea) using a knife coater with a gap of 6 mil (0.15 mm). The coated sample was placed in an oven at 70°C for 15 minutes. The final film thickness was 1 mil (0.03 mm).

35

5

EXAMPLE 15 (EX-15):

Example 15 was prepared similarly to CE-1, only using the components and amounts listed in Table 3. All components were added in a glass vial with toluene to make a solution with 40% solids. The vial was then sealed and contents were mixed overnight. The solution was then coated according to the same coating procedure outlined in CE-1.

Example Set 5 (comparative acrylic adhesive)

COMPARATIVE EXAMPLE 4 (CE-4):

In a clear glass jar, 300 g of 2-EHA (Aldrich, St. Louis, MO, USA), 60 g of Isobornyl Acrylate (Sartomer, Exton, PA, USA) and 40 g of hydroxyethyl acrylate (BASF Corp, Florham Park, NJ, USA) and 0.16 g of D1173 photoinitiator (BASF Corp, Florham Park, NJ, USA) were mixed (formulation information is provided in Table 4). The sample was purged with nitrogen for 5 minutes and exposed to low intensity (0.3 mW/cm^2) UV from a 360 nm LED light until a coatable viscosity ($\sim 2000 \text{ cPs}$) was achieved. The polymerization was halted by turning off the LED light and purging with air for 60 seconds. An additional 0.6 g of IRGACURE 651 photoinitiator (BASF Corp, Florham Park, NJ, USA) and 0.6 g of hexanedioldiacrylate crosslinker (Aldrich, St. Louis, MO, USA) was then added to the formulation. To 8 g of this polymer, 1.8 g of 1192H and 0.2 g of SR833S were added. The viscous polymer solution was then coated between siliconized polyester release liners, RF02N and RF22N (SKC Haas, Korea), using a knife coater with a set gap to yield an adhesive with coating thickness of $50 \mu\text{m}$ and then irradiated with 1.5 J/cm^2 dose using a 360 nm light source. The final film thickness was 1 mil (0.03 mm).

Example Set 6 (SIBS with multifunctional acrylates)

EXAMPLES 16 to 23 (EX-16 to EX-23)

Examples 16 - 23 were prepared similarly to CE-1, only using the components and amounts listed in Tables 10 and 11. For each example, all components were added in a glass vial with toluene to make a solution with 40% solids. The vial was then sealed and contents were mixed overnight. The solutions were then individually coated according to the same coating procedure outlined in CE-1.

35

Example Set 7

COMPARATIVE EXAMPLE 24 and EXAMPLE 25 (CE-24 to EX-25)

Comparative Example 24 and Example 25 were prepared similarly to CE-1, only using the components and amounts listed in Table 13. For each example, all components were added in a

- 5 glass vial with toluene to make a solution with 40% solids. The vial was then sealed and contents were mixed overnight. The solutions were then individually coated according to the same coating procedure outlined in CE-1.

The composition for EX-25 appeared hazy.

10

TABLE 2 Example Sets 1 and 2 Formulations

Sample ID	SIBS 103T, g (wt%)	OB15, g (wt%)	OB10, g (wt%)	E5300, g (wt%)	M1192H, g (wt%)	SR833S, g (wt%)	TPO-L, g (wt%)
CE-1		8, (66.4%)		2, (16.6%)	1.8, (14.9%)	0.2, (1.7%)	0.05, (0.4%)
EX-1	7.2, (59.8%)	0.8, (6.6%)		2, (16.6%)	1.8, (14.9%)	0.2, (1.7%)	0.05, (0.4%)
EX-2	4, (33.2%)	4, (33.2%)		2, (16.6%)	1.8, (14.9%)	0.2, (1.7%)	0.05, (0.4%)
EX-3	0.8, (6.6%)	7.2, (59.8%)		2, (16.6%)	1.8, (14.9%)	0.2, (1.7%)	0.05, (0.4%)
EX-4	8, (66.4%)			2, (16.6%)	1.8, (14.9%)	0.2, (1.7%)	0.05, (0.4%)
CE-2	7.2, (72.0%)		0.8, (8.0%)	2, (20.0%)			
EX-5	7.2, (39.9%)		0.8, (4.4%)	2, (11.1%)	7.2, (39.9%)	0.8, (4.4%)	0.05, (0.3%)
EX-6	7.2, (51.2%)		0.8, (5.7%)	2, (14.2%)	3.6, (25.6%)	0.4, (2.8%)	0.05, (0.4%)
EX-7	7.2, (59.8%)		0.8, (6.6%)	2, (16.6%)	1.8, (14.9%)	0.2, (1.7%)	0.05, (0.4%)

5

TABLE 3. Example Sets 3 and 4 Formulations

Sample ID	SIBS 102T, g (wt%)	OB10, g (wt%)	E5300, g (wt%)	M1192H, g (wt%)	PTPBA, g (wt%)	BNP, g (wt%)	SR833S, g (wt%)	TPO-L, g (wt%)
CE-3	7.2, (72.0%)	0.8, (8.0%)	2, (20.0%)					
EX-8	7.2, (59.8%)	0.8, (6.6%)	2, (16.6%)	1, (8.3%)		1, (8.3%)		0.05, (0.4%)
EX-9	7.2, (59.8%)	0.8, (6.6%)	2, (16.6%)		1, (8.3%)	1, (8.3%)		0.05, (0.4%)
EX-10	7.2, (59.8%)	0.8, (6.6%)	2, (16.6%)	1, (8.3%)			1, (8.3%)	0.05, (0.4%)
EX-11	7.2, (59.8%)	0.8, (6.6%)	2, (16.6%)	2, (16.6%)				0.05, (0.4%)
EX-12	7.2, (59.8%)	0.8, (6.6%)	2, (16.6%)		2, (16.6%)			0.05, (0.4%)
EX-13	7.2, (59.8%)	0.8, (6.6%)	2, (16.6%)			2, (16.6%)		0.05, (0.4%)
EX-14	6, (59.7%)		2, (19.9%)		1, (10.0%)		1, (10.0%)	0.05, (0.5%)
EX-15	6, (59.7%)		2, (19.9%)		1, (10.0%)		1, (10.0%)	0.05, (0.5%)

TABLE 4. Comparative acrylic adhesive

Sample ID	2-EHA, g (wt%)	IBOA, g (wt%)	HEA, g (wt%)	D1173, g (wt%)	I651, g (wt%)	HDDE, g (wt%)	M1192H, g (wt%)	SR833S, g (wt%)
CE-4	5.98, (59.8%)	1.20, (12.0%)	0.80, (8.0%)	0.003, (0.03%)	0.01, (0.1%)	0.01, (0.1%)	1.8, (18.0%)	0.2, (2.0%)

10

5

TABLE 5. Example Set 1

Sample ID	Haze, %	WVTR, g/m ² /day	RI
CE-1	11.23	4	1.533
EX-1	0.4	17.4	1.552
EX-2	0.98	21.58	1.558
EX-3	1.3	5.9	1.533
EX-4	0.31	18.6	1.555

TABLE 6. Example Set 2

Sample ID	Haze, %	WVTR, g/m ² /day	RI
CE-2	0.32	14.77	1.540
EX-5	0.36	26.12	1.578
EX-6	0.29	25.59	1.563
EX-7	0.41	17.88	1.551

10

TABLE 7. Example Set 3

Sample ID	Haze, %	WVTR, g/m ² /day	RI
CE-3	0.31	11.53	1.533
EX-8	0.42	13.9	1.547
EX-9	0.28	14.1	1.546
EX-10	0.51	15.2	1.537
EX-11	0.38	17.8	1.548
EX-12	0.47	16.9	1.550
EX-13	0.31	14.72	1.549

TABLE 8. Example Set 4

Sample ID	Haze, %	WVTR, g/m ² /day	RI
EX-14	0.35	13.9	1.541
EX-15	0.32	12.8	1.552

5

TABLE 9. Comparative acrylic adhesive vs. acrylates

Sample ID	Haze, %	WVTR, g/m ² /day	RI
CE-4	0.35	1281	1.5049
EX-1	0.4	17.4	1.552

TABLE 10. Example Set 6, EX 16-18

Sample ID	SIBS 102T, g (wt%)	OB10, g (wt%)	E5300, g (wt%)	HDDA, g (wt%)	TPO-L, g (wt%)
EX-16	8, (66.4%)		2, (16.6%)	2, (16.6%)	0.05, (0.4%)
EX-17	10, (83.0%)			2, (16.6%)	0.05, (0.4%)
EX-18	7.2, (59.8%)	0.8, (6.6%)	2, (16.6%)	2, (16.6%)	0.05, (0.4%)

TABLE 11. Example Set 6, EX-19 to EX-23

Sample ID	SIBS 102T, g (wt%)	E5300, g (wt%)	SR340, g (wt%)	SR339, g (wt%)	OPPEA, g (wt%)	PHPM, g (wt%)	CVE, g (wt%)
EX-19	8 (66.6 %)	2 (16.7 %)	2 (16.7 %)				
EX-20	8 (66.6 %)	2 (16.7 %)		2 (16.7 %)			
EX-21	8 (66.6 %)	2 (16.7 %)			2 (16.7 %)		
EX-22	8 (66.6 %)	2 (16.7 %)				2 (16.7 %)	
EX-23	8 (66.6 %)	2 (16.7 %)					2 (16.7 %)

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TABLE 12. Example Set 6

Sample ID	Haze, %	WVTR, g/m ² /day
EX-16	8.1	18.1
EX-17	10.3	19.8
EX-18	6.2	13.2
EX-19	0.45	NM
EX-20	0.44	NM
EX-21	0.38	NM
EX-22	6.8	NM
EX-23	2.13	NM

NM = not measured.

TABLE 13. Example Set 7

Sample ID	SIBS 102T, g (wt%)	E5300, g (wt%)	SR492, g (wt%)	I651, g (wt%)
CE-24	8 (80.0 %)	2 (20.0 %)		
EX-25	8 (59.3 %)	2 (14.8 %)	3 (22.2 %)	0.5 (3.7 %)

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TABLE 14. Example Set 7

Sample ID	Peel Adhesion on SS, N/dm	G' at 25 °C, Pa	Tan delta at 150 °C
CE-24	4.3	217,000	0.51
EX-25	3.1	287,000	0.37

All cited references, patents, and patent applications in the above application for letters patent are herein incorporated by reference in their entirety in a consistent manner. In the event of inconsistencies or contradictions between portions of the incorporated references and this application, the information in the preceding description shall control. The preceding description, given in order to enable one of ordinary skill in the art to practice the claimed disclosure, is not to be construed as limiting the scope of the disclosure, which is defined by the claims and all equivalents thereto.

5 **What is claimed is:**

1. A composition comprising
a styrene-isobutylene block copolymer; and
at least one ethylenically unsaturated monomer comprising one or more groups selected from
(meth)acryl or vinyl ether.

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2. The composition of claim 1 wherein the ethylenically unsaturated monomer is a
monofunctional ethylenically unsaturated monomer.

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3. The composition of claims 1-2 wherein the ethylenically unsaturated monomer is a
multifunctional ethylenically unsaturated monomer.

4. The composition of claims 1-3 wherein the ethylenically unsaturated monomer is aliphatic.

5. The composition of claims 1-3 wherein the ethylenically unsaturated monomer is aromatic.

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6. The composition of claims 1-5 wherein the ethylenically unsaturated monomer has a refractive
index of at least 1.50, 1.55, or 1.60.

7. The composition of claims 1-6 wherein the ethylenically unsaturated monomer has a
hydrophilic-lipophilic balance (HLB) according to Griffin's method ranging from 3.7 to 7.3.

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8. The composition of claim 7 wherein the ethylenically unsaturated monomer has a HLB
according to Griffin's method of at least 3.8, 3.9 or 4.0.

9. The composition of claims 1-8 wherein the ethylenically unsaturated monomer has a Log P
according to Moriguchi's method ranging from 1.8 to 6.

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10. The composition of claim 9 wherein the ethylenically unsaturated monomer has a Log P
according to Moriguchi's method no greater than 5.5, 5.0, 4.5, or 4.0.

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11. The composition of claims 1-10 wherein the composition comprises 5 wt.-% to 95 wt.-% of
styrene-isobutylene-styrene block copolymer (SIBS).

- 5 12. The composition of claims 1-11 wherein the composition further comprises a second polyisobutylene polymer lacking polymerized units comprising styrenic groups.
13. The composition of claims 1-12 wherein the weight ratio of styrene-isobutylene block copolymer to second polyisobutylene polymer of the adhesive composition ranges from 15:1 to
10 1:15.
14. The composition of claim 13 wherein the weight ratio of styrene-isobutylene block copolymer to second polyisobutylene polymer of the adhesive composition is greater than 2.2:1.
- 15 15. The composition of claims 1-14 wherein the polyisobutylene polymer comprises one or more polyisobutylene polymers having a weight average molecular weight ranging from 15,000 g/mole to 300,000 g/mole.
16. The composition of claims 1-15 wherein the composition further comprises one or more
20 additives.
17. The composition of claim 16 wherein the additive is a tackifier.
18. The composition of claims 1-17 wherein the composition further comprises at least one free-
25 radical initiator.
19. A composition comprising
a styrene-isobutylene block copolymer; and
polymerized units of at least one ethylenically unsaturated monomer comprising one or more
30 groups selected from (meth)acryl or vinyl ether.
20. The composition of claim 19 wherein the composition is further characterized according to claims 2-18.
- 35 21. The composition of claims 1-20 wherein the composition at a thickness of 50 microns has a water vapor transmission rate of less than 100 g/m² day at 40°C and 100% relative humidity.
22. The composition of claims 1-21 wherein the composition at a thickness of 50 microns has a haze of less than 1, 1.5 1, or 0.5%

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23. The composition of claims 1-22 wherein the composition is an adhesive.

24. The composition of claims 1-23 wherein the composition is a pressure sensitive adhesive having a storage modulus G' of less than 0.3 MPa at a temperature of 25°C and a frequency of 1 hertz.

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25. The composition of claims 1-24 wherein the composition is a pressure sensitive adhesive having an initial 180 degree peel adhesion of 0.1N/dm.

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26. A method of making an article comprising providing a composition comprising a styrene-isobutylene block copolymer and at least one ethylenically unsaturated monomer according to claims 1-25; applying the composition to a substrate; optionally curing the at least one ethylenically unsaturated monomer.

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27. The method of claim 26 wherein the composition further comprises a free-radical initiator and the method comprises curing the ethylenically unsaturated monomer by exposing the composition to actinic radiation.

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28. An article comprising:
a substrate; and
the composition of claims 1-25 disposed on the substrate.

29. The article of claim 28 wherein the substrate is a release liner, a film, or an electronic component.

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30. A method of bonding comprising providing a composition according to claims 1-25; and bonding a substrate to a second substrate or surface with the composition.

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